PRELIMINARY SPEC

### OVAL SOLID STATE LAMP

Part Number: WP5603SIDL/SD/J HYPER ORANGE

### Description **Features** The Super Bright device is based on a light emitting diode •OUTSTNDING MATERIAL EFFICIENCY. chip made from AIGaInP and bonded on silicon substrate. •RELIABLE AND RUGGED. •I.C. COMPATIBLE/LOW CURRENT CAPABILITY. •RoHS COMPLIANT. ·Com.cn **Package Dimensions** 25[0.984]MIN. 7[.276] 3.8[0.15] 1.5 MAX 1.5[0.06]TYP CATHODE .2[.205] .54[0.1 ഫ 0.7MAX. □0.5[0.02] ±0.05 Notes: 1. All dimensions are in millimeters (inches). 3. Lead spacing is measured where the leads emerge from the package. 4. Specifications are subject to change without notice.

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#### **Selection Guide** lv (mcd) [2] @ 20mA Viewing Angle [1] Part No. Dice Lens Type 201/2 Min. TYP. 100°(H) WP5603SIDL/SD/J HYPER ORANGE (AlGaInP) **RED SEMI DIFFUSED** 1800 3600 50°(V)

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

2. Luminous intensity/ luminous Flux: +/-15%.

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Orange	640		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Orange	630	1.16	n <b>m</b>	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Orange	25	39	nm	IF=20mA
С	Capacitance	Hyper Orange	27	-0-	pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Orange	2.2	2.8	V	IF=20mA
lr	Reverse Current	Hyper Orange		10	uA	VR = 5V
Notes: 1.Wavelength: 2. Forward Volt		3		l	L	

### Absolute Maximum Ratings at TA=25°C

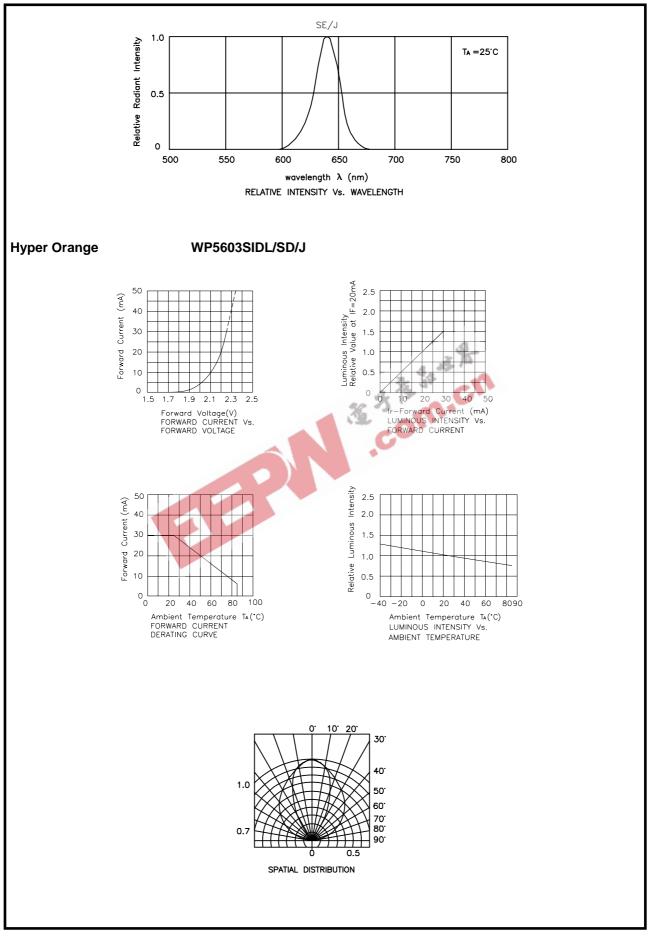
Parameter	Hyper Orange	Units		
Power dissipation	84	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.



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